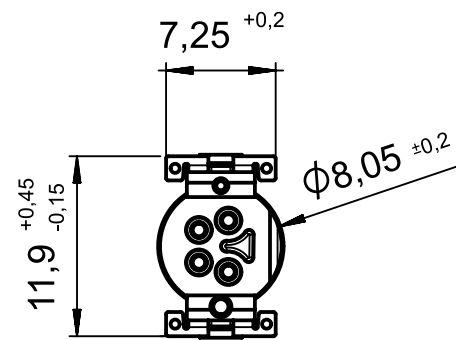
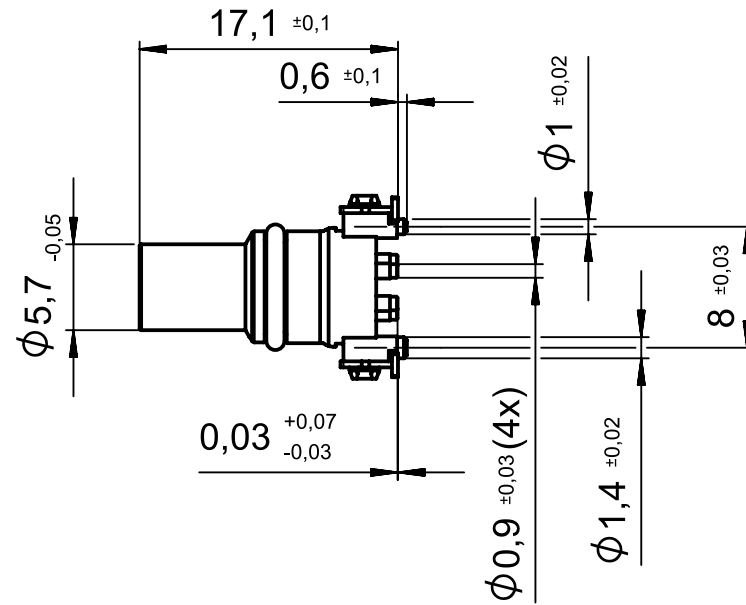
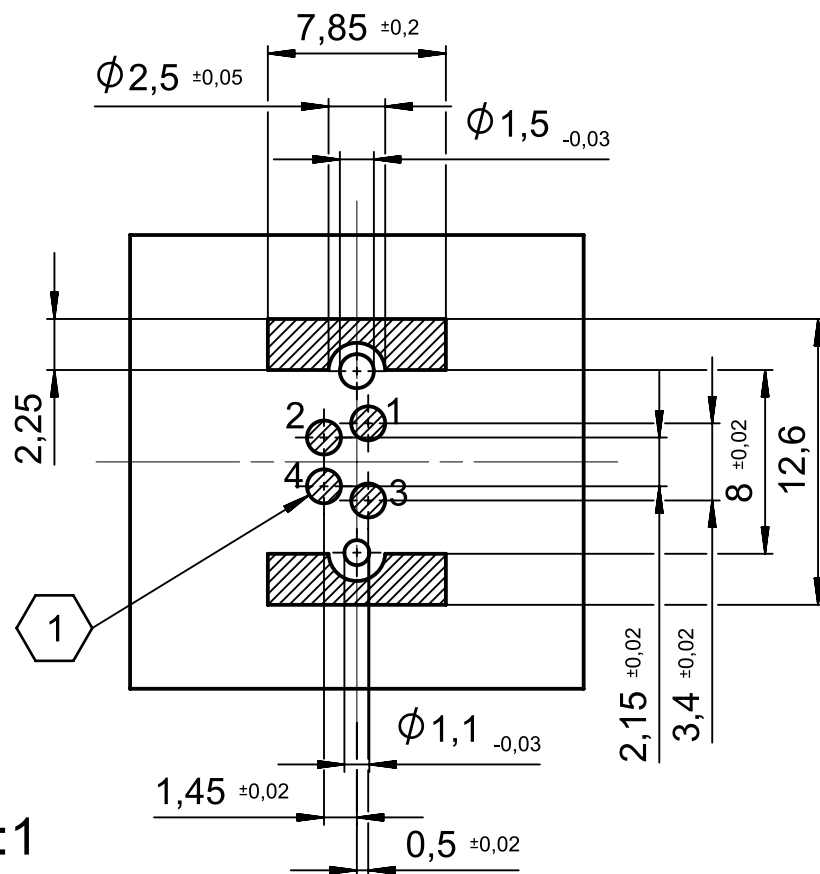


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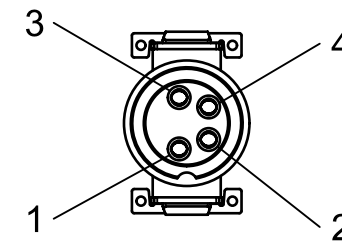
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PCB-layout
(advice)



socket face female



Coplanarity of all contacts and anchor plate  0.1

Recommended solder paste thickness 150µm

 Further information on soldering process and recommended layout, see brochure "Connectors for SMT production"

- EN ISO 291 23/50

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